ON Semiconductor®

Final Product/Process Change Notification

Document #: FPCN22577Z2
Issue Date: 09 Sep 2020

Title of Change:	Update to FPCN22577Z - Cancellation of previously announced Transfer of Assembly and Test operations of Cebu former Fairchild SC70 package to ON Semiconductor Leshan, China and change the backmetal site from Bucheon, Korea to ON Niigata, Japan.
Proposed Changed Material First Ship Date:	09 Sep 2020 or earlier if approved by customer
Current Material Last Order Date:	NA *Orders received after the Current Material Last Order Date expiration are to be considered as orders for new changed material as described in this PCN. Orders for current (unchanged) material after this date will be per mutual agreement and current material inventory availability*.
Current Material Last Delivery Date:	NA *The Current Material Last Delivery Date may be subject to change based on build and depletion of the current (unchanged) material inventory*
Product Category:	Active components – Discrete components
Contact information:	Contact your local ON Semiconductor Sales Office or Peter.Lee@onsemi.com
PCN Samples Contact:	Contact your local ON Semiconductor Sales Office to place sample order or PCN.samples@onsemi.com Sample requests are to be submitted no later than 45 days after publication of this change notification. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.
Sample Availability Date:	NA
PPAP Availability Date:	NA
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or ChangKit.Mok@onsemi.com
Type of Notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 12 months prior to implementation of the change or earlier upon customer approval. ON Semiconductor will consider this proposed change and it's conditions acceptable, unless an inquiry is made in writing within 45 days of delivery of this notice. To do so, contact PCN.Support@onsemi.com.

Change Category

Category	**Type of Change**
Process - Wafer Production	Change in process technology (e. g. process changes like lithography, etch, oxide deposition, diffusion, die back surface preparation/backgrind, ...)
Test Flow	Move of all or part of electrical wafer test and/or final test to a different location/site/subcontractor
Process - Assembly	Move of all or part of assembly to a different location/site/subcontractor., Change of leadframe base material, Change of encapsulation/sealing material, Change of product marking

Description and Purpose:

This update is to notify customers that the intended changes previously communicated in FPCN22577Z has been cancelled due to the change of ON semi supply strategy.

FPCN22577Z included the following description:

"Transfer of Assembly and Test operations of Cebu former Fairchild SC70 package to ON Semiconductor Leshan, China and change the backmetal site from Bucheon, Korea to ON Niigata, Japan."

The intended change described above will not be implemented.

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Reason / Motivation for Change:	Cancellation of a Previous PCN
Anticipated impact on fit, form, function, reliability, product safety or manufacturability:	The device has been qualified and validated based on the same Product Specification. The device has successfully passed the qualification tests. Potential impacts can be identified, but due to testing performed by ON Semiconductor in relation to the PCN, associated risks are verified and excluded. No anticipated impacts.

Sites Affected:

ON Semiconductor Sites	**External Foundry/Subcon Sites**
Leshan Phoenix Semiconductor, China	None
ON Semiconductor Niigata, Japan	

Marking of Parts/ Traceability of Change:	ON Semiconductor format

Reliability Data Summary:

NA

Electrical Characteristics Summary:

Electrical characteristics are not impacted.

List of Affected Parts:

Note: *Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the* ***PCN Customized Portal****.*

Current Part Number	New Part Number	Qualification Vehicle
FDG6301N-F085	NA	FDG6301N-F085
FDG6301N-F085P	NA	FDG6301N-F085
FDG6332C-F085	NA	FDG6332C-F085
FDG6332C-F085P	NA	FDG6332C-F085